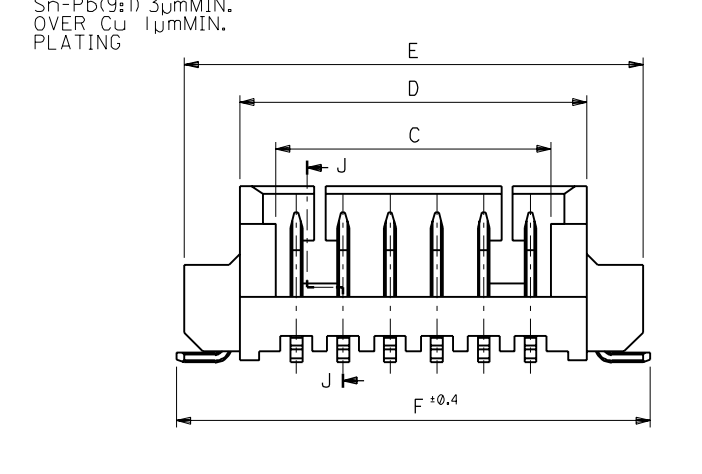
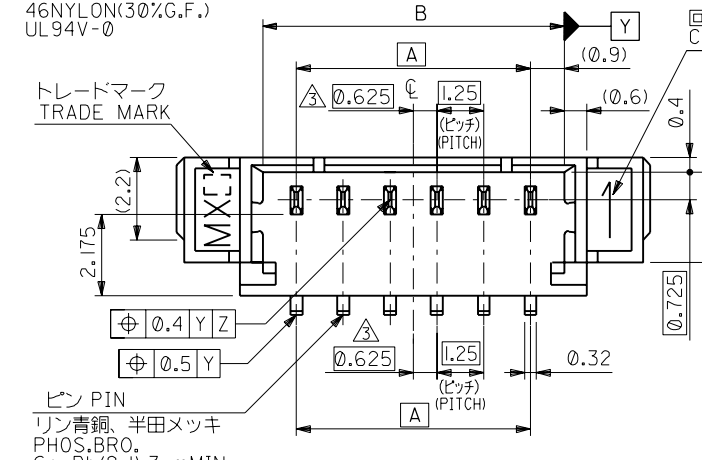
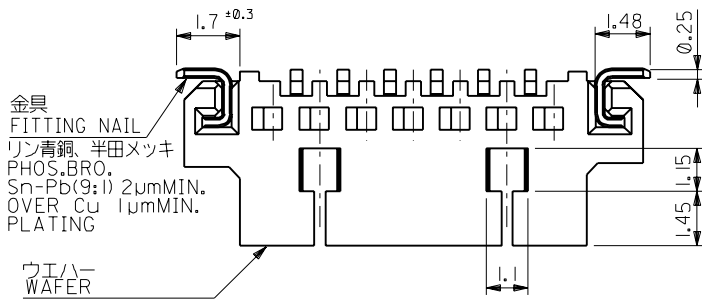


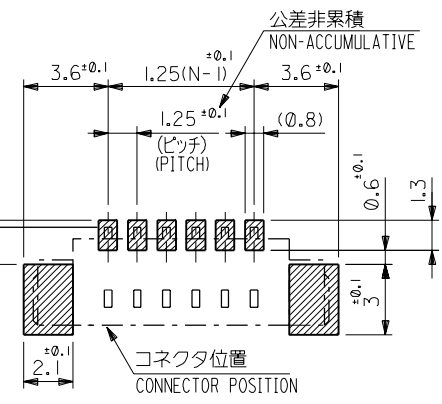
DWG. NO. SD-53398-**-10

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

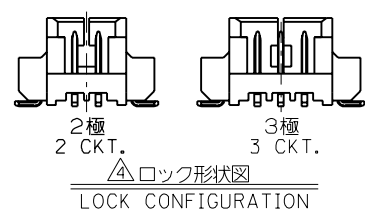
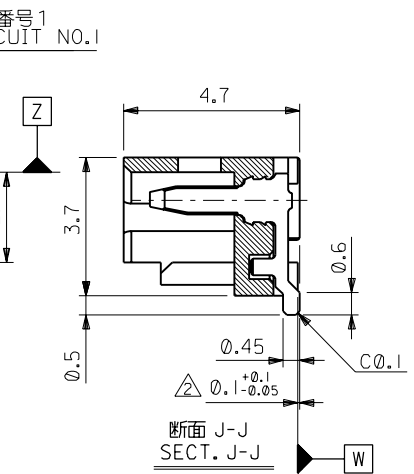


注記 NOTES

1. 嵌合相手: 51021 シリーズ MATE WITH : 51021 SERIES
- △ 水平面上においての、ウエハー底面 [W] とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
- △ 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。 LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS. TWO PLACES FOR MORE THAN 4 CKTS.



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



23.9	23.5	20.5	18.6	19.3	17.5	53398-1510	15
22.65	22.25	19.25	17.35	18.05	16.25	-1410	14
21.4	21	18	16.1	16.8	15	-1310	13
20.15	19.75	16.75	14.85	15.55	13.75	-1210	12
18.9	18.5	15.5	13.6	14.3	12.5	-1110	11
17.65	17.25	14.25	12.35	13.05	11.25	-1010	10
16.4	16	13	11.1	11.8	10	-0910	9
15.15	14.75	11.75	9.85	10.55	8.75	-0810	8
13.9	13.5	10.5	8.6	9.3	7.5	-0710	7
12.65	12.25	9.25	7.35	8.05	6.25	-0610	6
11.4	11	8	6.1	6.8	5	-0510	5
10.15	9.75	6.75	4.85	5.55	3.75	-0410	4
8.9	8.5	5.5	3.6	4.3	2.5	-0310	3
7.65	7.25	4.25	2.35	3.05	1.25	53398-0210	2
F	E	D	C	B	A	ENG. NO.	極数 NO. OF CKTS.

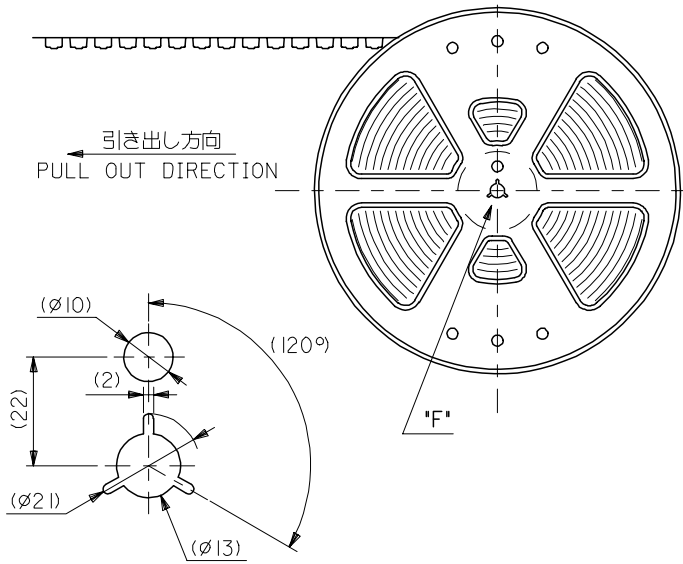
角度 ANGLE	±3°	変更 REVISION	記号 LTR	変更内容 REVISION RECORD	DR. 日付 DATE	材料 MATERIAL	図中参照 SEE DRAWING
30以上 OVER	+0.3	F 変更 REVISION	WC2000-0636		K.K. 100/3/30	仕上げ FINISH	—
10以上 30未満 UNDER	+0.25	E 変更 REVISION	WC800048		M.F. 97/7/5		
10未満 UNDER	+0.2	D 変更 REVISION	U31030		H.H. 93/10/13	適用電線範囲 WIRE RANGE	—
新規作成 RELEASED		C 変更 REVISION	U30753		K.T. 93/7/29		
一般公差 GENERAL TOLERANCES		B 変更 REVISION	U30610		K.T. 93/6/18	被覆外径 INS. RANGE	—
		A 変更 REVISION	U30230		H.H. 93/3/10		
		0 新規作成 RELEASED	U20942		K.T. 92/10/12	DRAWN BY '92/10/12	CHK'D BY '00/3/30
					K.T. 92/10/12	K.TOJO	T.YAMAGUCHI
					M.F. 00/3/30	APP'D BY '00/3/30	尺度 SCALE

molex MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

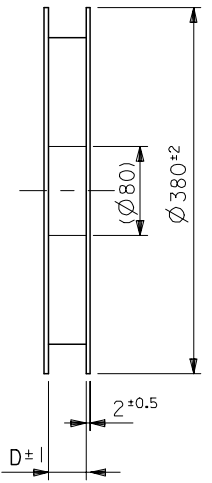
REVISE ONLY ON CAD SYSTEM
TITLE 名称

1.25 WIRE TO BOARD CONN.
WAFER ASS'Y FOR SMT (ST.)

DWG. NO. SD-53398-**-10 REV F

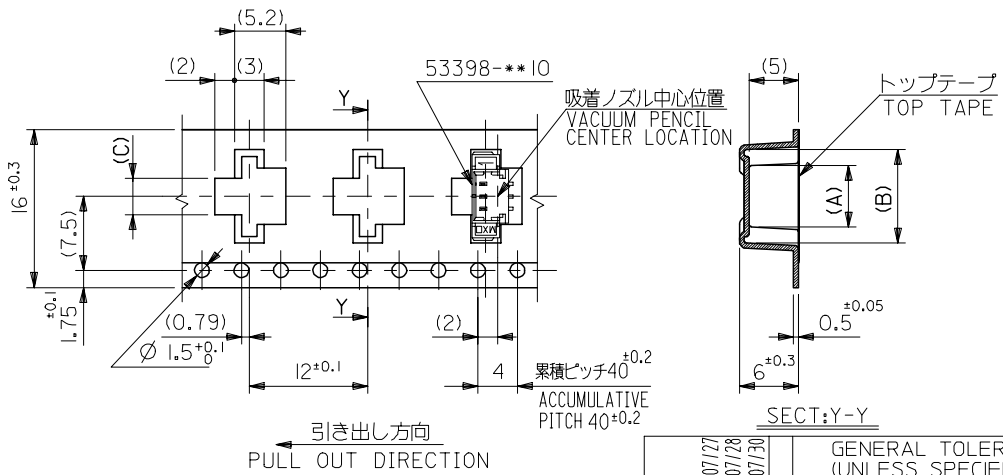


DETAIL "F"



NOTES

1. 梱包数量：1000個/リール
NUMBER OF CONNECTOR:1000PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH
3. トップテープの剥離強度：0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE:0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
 <剥離速度：300mm/min(参考)>
PEELING SPEED:300mm/min.
(REFERENCE)
4. 53398-**10 の詳細寸法については図面 SD-53398-**10 を参照下さい。
RE DETAILED DIMENSIONS,SEE SD-53398-**10.
5. 材料 (MATERIAL)
キャリアテープ(CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)
トップテープ (TOP TAPE): PET ,PE ,PEF
リール (REEL):ポリスチレン (P S) <リサイクル材含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>



16幅テープ (TAPE WIDTH:16)

16	17.4	3.7	9.5	5.8	53398-0390	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	ENG. NO.	種数 CKT.
		2.45	8.25	4.55	53398-0290	2

REVISED EC NO: DRAWN:MERIGUCHI CHK'D:K.ASAKAWA APPR:S.ICHIKAWA 2004/07/27 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	---	METRIC	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	±0.25	K.TOJO	'93/04/13	1.25 W/B CONN. WAFER ASS'Y FOR SMT. EMBOSSED TAPE PACKAGE	
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED	
ANGULAR	±3 °	YAMAGUCHI	'00/12/08			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE			
		FUKUSHIMA	'00/12/08			
		MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		SEE CHART	SD-53398-**90	1 OF 3		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

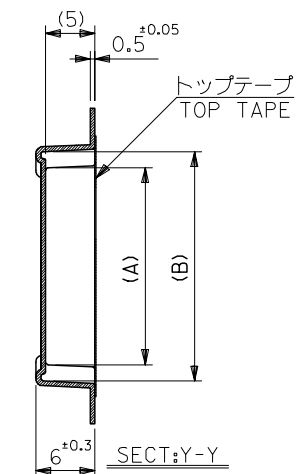
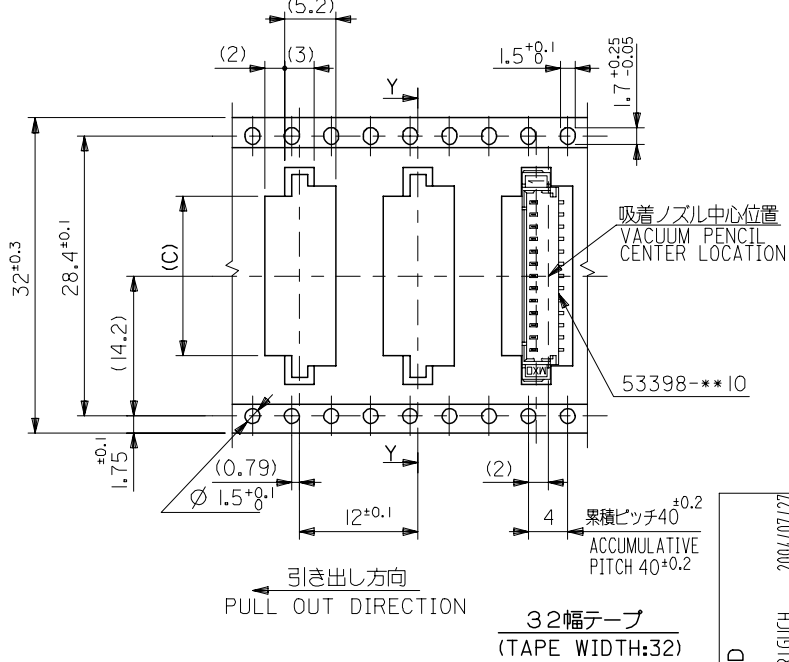
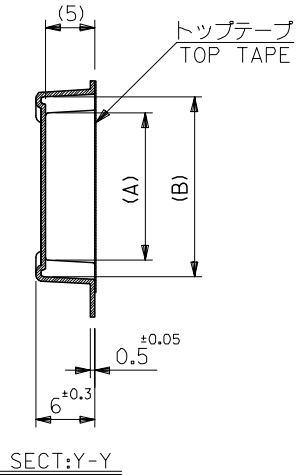
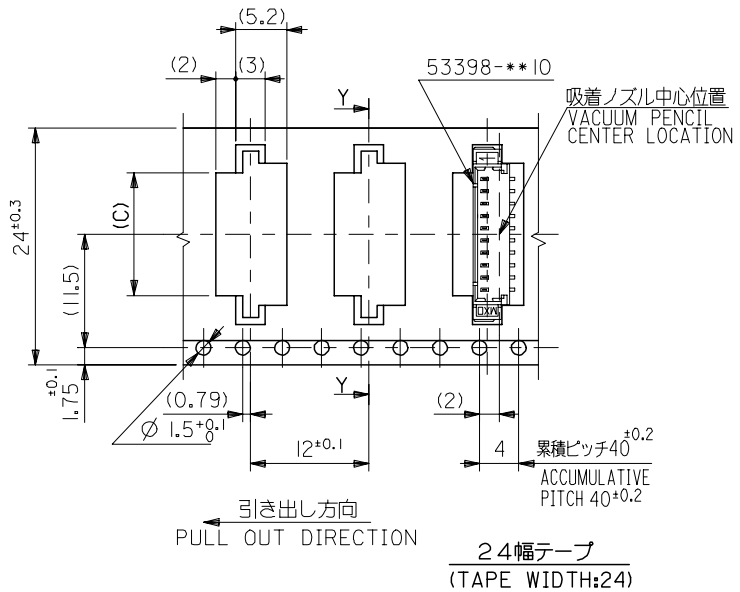
E

D

C

B

A



32	33.4	16.2	22	18.3	53398-1390	13
		14.95	20.75	17.05	-1290	12
		13.7	19.5	15.8	-1190	11
24	25.4	12.45	18.25	14.55	-1090	10
		11.2	17	13.3	-0990	9
		9.95	15.75	12.05	-0890	8
		8.7	14.5	10.8	-0790	7
		7.45	13.25	9.55	-0690	6
		6.2	12	8.3	-0590	5
		4.95	10.75	7.05	53398-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	ENG. NO.	種数 CKT.

REVISED EC NO: DRAWN BY: I GUCH CHKD BY: ASAKAW APP'R: S ICHIKAW REV	2004/07/27	2004/07/28	2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER			±0.2	DRAWN BY K. TOJO		DATE '93/04/13	TITLE 1.25 W/B CONN. WAFER ASS'Y FOR SMT. EMBOSSD TAPE PACKAGE			
	10 OVER 30 UNDER			±0.25	CHECKED BY YAMAGUCH		DATE '00/12/08	APPROVED BY FUKUSHIM			
	30 OVER			±0.3	APPROVED BY FUKUSHIM		DATE '00/12/08	MATERIAL NO. SEE CHART			
	ANGULAR			±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-53398-**90		SHEET NO. 2 OF 3		

10 9 8 7 6 5 4 3 2 1

F

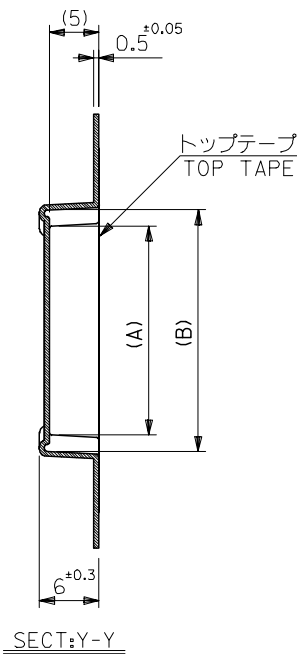
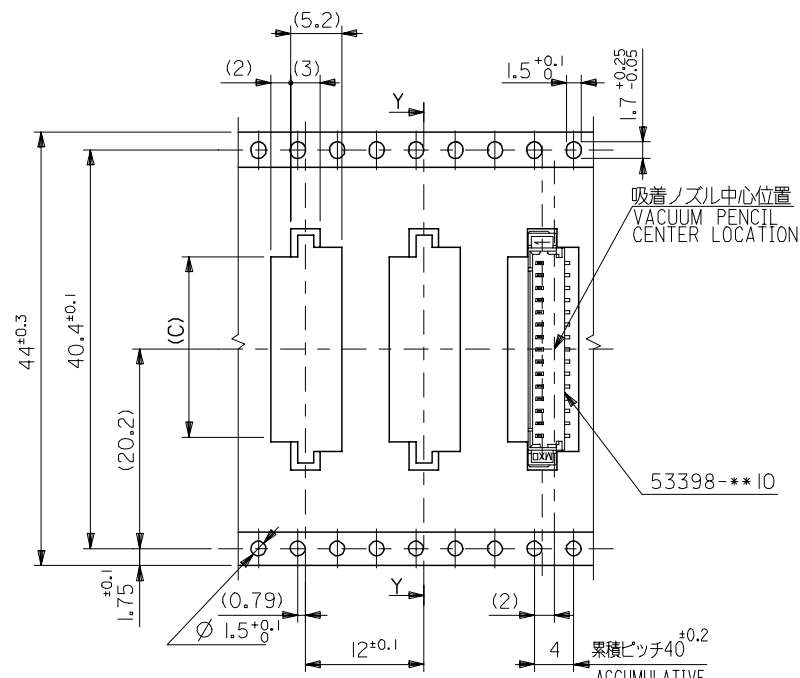
E

D

C

B

A



引き出し方向
PULL OUT DIRECTION

44幅テープ
(TAPE WIDTH:44)

累積ピッチ40±0.2
ACCUMULATIVE PITCH 40±0.2

44	45.4	18.7	24.5	20.8	53398-I590	I5
キャリアテープ幅 CARRIER TAPE WIDTH	D	17.45	23.25	19.55	53398-I490	I4
	(C)	(B)	(A)	ENG. NO.	種数 CKT.	

REVISED EC NO: DRAWN: M. I. GUCH 2004/07/27 CHK'D: K. ASAKAW 2004/07/28 APPR: S. ICHIKAW 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY K. TOJO		DATE '93/04/13	TITLE 1.25 W/B CONN. WAFER ASS'Y FOR SMT.	
	10 OVER 30 UNDER	±0.25	CHECKED BY YAMAGUCH		DATE '00/12/08	EMBOSSED TAPE PACKAGE	
	30 OVER	±0.3	APPROVED BY FUKUSHIM		DATE '00/12/08	MOLEX INCORPORATED	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53398-**90	SHEET NO. 3 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			